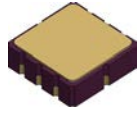


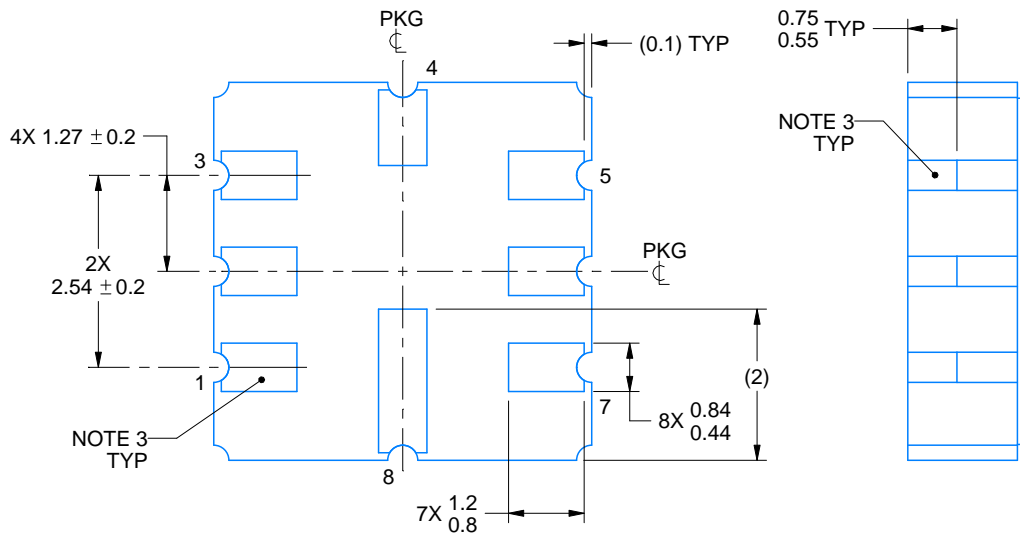
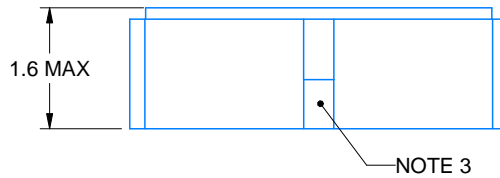
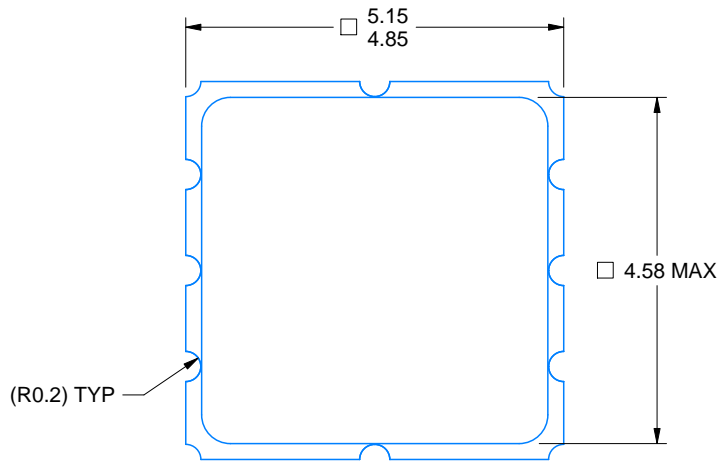
FKH0008A



# PACKAGE OUTLINE

LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



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NOTES:

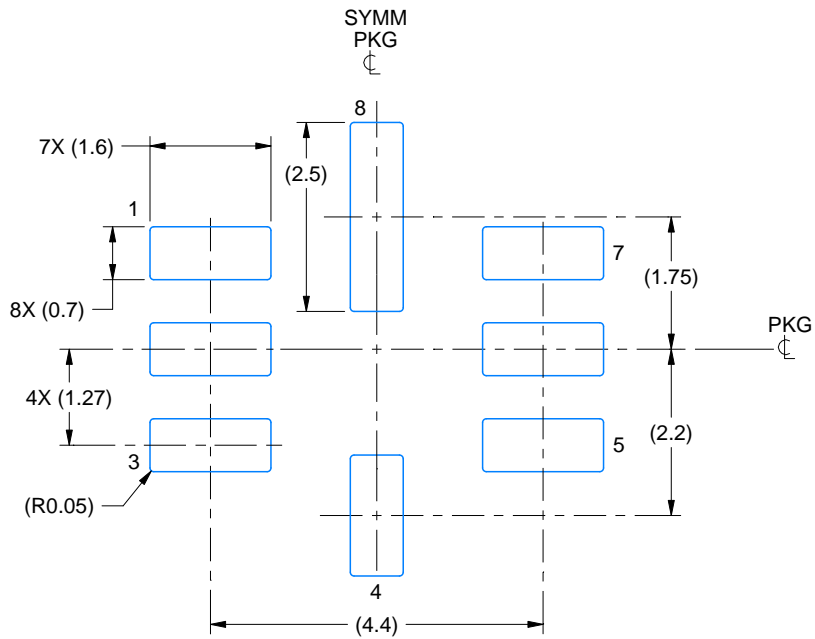
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M
2. This drawing is subject to change without notice.
3. Terminals are gold plated.

# EXAMPLE BOARD LAYOUT

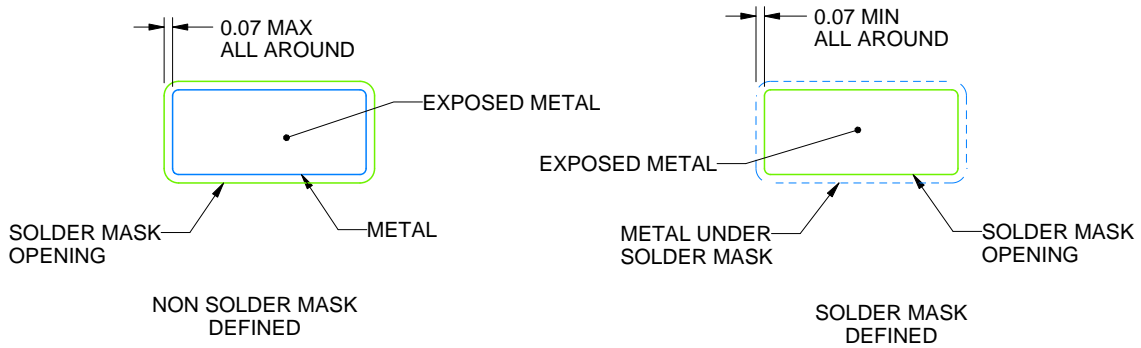
FKH0008A

LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:10X



SOLDER MASK DETAILS

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NOTES: (continued)

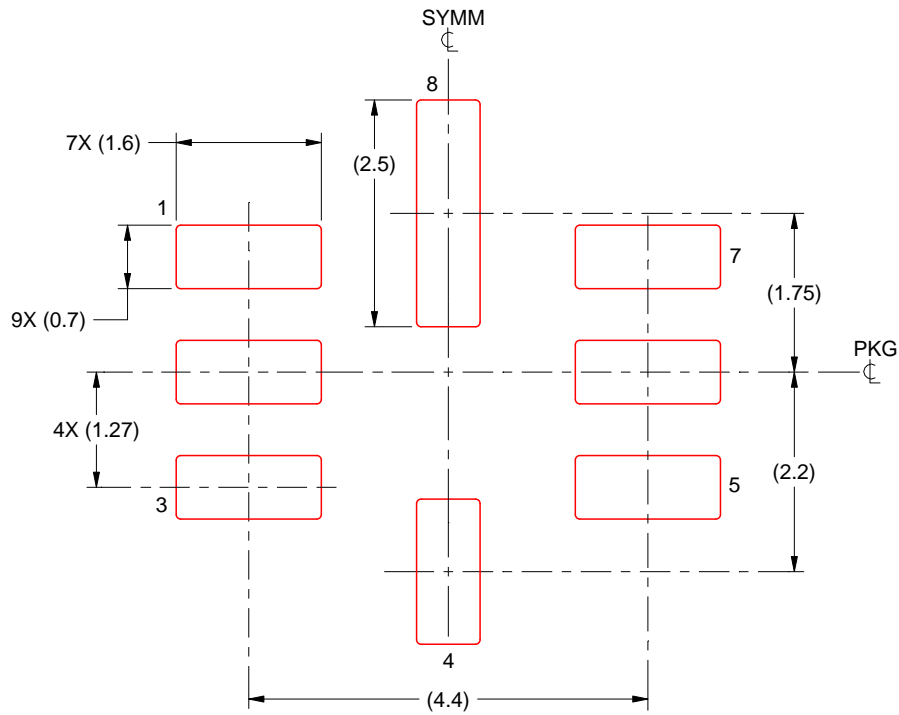
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

FKH0008A

LCCC - 1.6 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:12X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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